#### Remote 1

MSU Libraries • Remote Storage • Remote Storage • Remote Storage Michigan State University Libraries

#### **Preservation Environment Evaluation**

Type of Decay	Risks & Metrics	Evaluation & General Comments		
Natural Aging Chemical decay of organic materials	OK TWPI = 58	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity		
Mechanical Damage Physical damage to hygroscopic materials	GOOD  % DC = 0.27 % EMC min = 7.4 % EMC max = 8.3	Minimal risk of physical damage to most hygroscopic materials such as paintings, rare books and furniture.		
Mold Risk  Mold growth in area or on collection objects	GOOD  MRF = 0	Minimal risk of mold growth.		
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 8.3	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.		

## **Graphs**



### **Statistics**

Temperature		Relative Humidity		Dew Point	
T°F Mean	66.6	%RH Mean	42	DP°F Mean	42.6
T°F Median	67.6	%RH Median	42	DP°F Median	42.5
T°F Stdev	5.6	%RH Stdev	2	DP°F Stdev	4.6
T°F Min	54.6	%RH Min	34	DP°F Min	32.8
T°F Max	85.9	%RH Max	87	DP°F Max	59.6

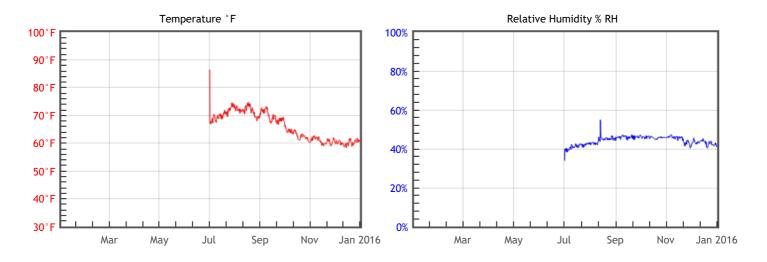
## Remote 2

MSU Libraries • Remote Storage • Remote Storage • Remote Storage Michigan State University Libraries

#### **Preservation Environment Evaluation**

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 56	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	GOOD  % DC = 0.26 % EMC min = 7.8 % EMC max = 8.7	Minimal risk of physical damage to most hygroscopic materials such as paintings, rare books and furniture.
Mold Risk  Mold growth in area or on collection objects	GOOD  MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 8.7	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

## **Graphs**



### **Statistics**

Temperature		Relative Humidity		Dew Point	
T°F Mean	66	%RH Mean	44	DP°F Mean	43.5
T°F Median	66.5	%RH Median	45	DP°F Median	43.4
T°F Stdev	5	%RH Stdev	2	DP°F Stdev	4.5
T°F Min	58.4	%RH Min	34	DP°F Min	36.5
T°F Max	86.5	%RH Max	55	DP°F Max	56.4

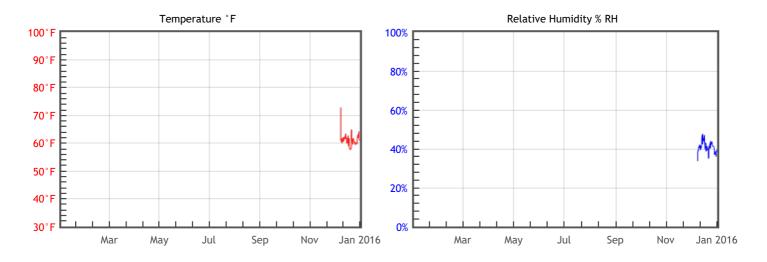
MSU Libraries • Remote Storage • Remote Storage • Remote Storage Michigan State University Libraries

# 23 days

#### **Preservation Environment Evaluation**

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	GOOD <b>TWPI =</b> 91	Slow rate of chemical decay in organic materials such as paper, leather, textiles, plastics and dyes
Mechanical Damage Physical damage to hygroscopic materials	GOOD  % DC = 0.43 % EMC min = 6.8 % EMC max = 8.3	Minimal risk of physical damage to most hygroscopic materials such as paintings, rare books and furniture.
Mold Risk Mold growth in area or on collection objects	GOOD  MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 8.3	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

## **Graphs**



### **Statistics**

Temperature		Relative Humidity		Dew Point	
T°F Mean	60.8	%RH Mean	41	DP°F Mean	37.1
T°F Median	60.8	%RH Median	41	DP°F Median	36.8
T°F Stdev	1.5	%RH Stdev	2	DP°F Stdev	1.8
T°F Min	57.6	%RH Min	34	DP°F Min	33
T°F Max	72.9	%RH Max	49	DP°F Max	43.7